

Features

Compared to the original manufacturer's product, Maxim's DG200A consumes significantly lower power, making it better suited for portable applications.

- ◆ Improved 2nd Source! Power Supply Current $< 300\mu\text{A}$
- ◆ Wide Supply Range $\pm 4.5\text{V}$ to $\pm 18\text{V}$
- ◆ Single Supply Operation
- ◆ Non-Latching with Supplies Turned-off and Input Signals Present
- ◆ CMOS and TTL Logic Compatible
- ◆ Monolithic, Low Power CMOS Design

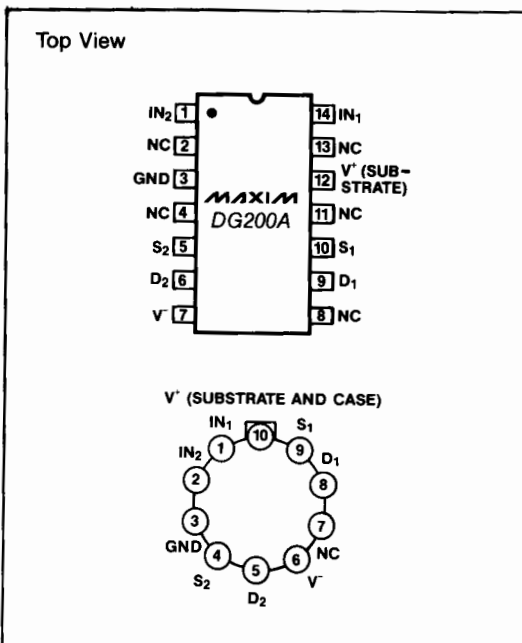
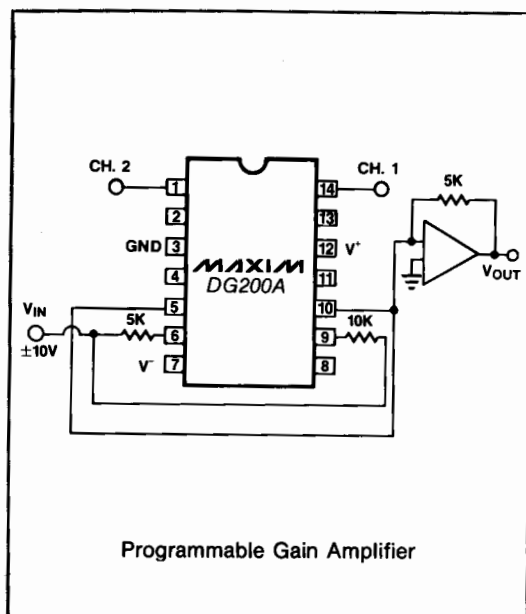
Applications

- Winchester Disk Drives
Test Equipment
Communications Systems
PBX, PABX
Guidance and Control Systems
Head up Displays
Military Radios

PART	TEMP. RANGE	PIN-PACKAGE
DG200AAK	-55°C to +125°C	14 Lead Cerdip
DG200ARK	-25°C to +85°C	14 Lead Cerdip*
DG200ACK	0°C to +70°C	14 Lead Cerdip
DG200ACJ	0°C to +70°C	14 Lead Plastic DIP
DG200ADJ	-40°C to +85°C	14 Lead Plastic DIP
DG200ACY	0°C to +70°C	14 Lead SO
DG200ADY	-40°C to +85°C	14 Lead SO
DG200AC/D	0°C to +70°C	Dice
DG200AAA	-55°C to +125°C	10 Pin Metal Can*
DG200ABA	-25°C to +85°C	10 Pin Metal Can*
DG200ACA	0°C to +70°C	10 Pin Metal Can*

*Contact factory for availability.

Pin Configuration



DG200A

Dual Monolithic SPST CMOS Analog Switch

ABSOLUTE MAXIMUM RATINGS

Voltages Referenced to V^-	
V^+	44V
GND	25V
Digital Inputs V_S , V_D (Note 1)	-2V to ($V^+ + 2V$) or 20mA, whichever occurs first.
Current, Any Terminal Except S or D	30mA
Continuous Current, S or D	20mA
(Pulsed at 1msec, 10% duty cycle max)	100mA
Storage Temperature (A & B Suffix)	-65 to 150°C
(C Suffix)	-65 to 125°C

Operating Temperature (A Suffix)	-55 to 125°C
(B Suffix)	-25 to 85°C
(C Suffix)	-25 to 85°C
(D Suffix)	-40 to 85°C

Power Dissipation (Package)*	
Metal Can**	450mW
14 Pin Ceramic DIP***	825mW
14 Pin Plastic DIP****	470mW

* All leads soldered or welded to PC board.

** Derate 6mW/°C above 75°C.

*** Derate 11mW/°C above 75°C.

**** Derate 6.5mW/°C above 25°C.

Stresses listed under "Absolute Maximum Ratings" may be applied (one at a time) to devices without resulting in permanent damage. These are stress ratings only, and functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS ($V^+ = +15V$, $V^- = -15V$, GND = 0V, $T_A = 25^\circ C$, unless otherwise indicated.)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS						UNITS	
			DG200A			DG200 B/C/D				
			MIN	TYP	MAX	MIN	TYP	MAX		
			(Note 2) (Note 3)			(Note 2) (Note 3)				
SWITCH										
Analog Signal Range (Note 1)	V _{ANALOG}			-15		15	-15		15	V
Drain-Source ON Resistance	r _{DS(on)}	V _D = ±10V, V _{in} = 0.8V, I _S = 1mA			45	70		45	80	Ω
Source OFF Leakage Current	I _{S(off)}	V _{in} = 2.4V	V _S = 14V, V _D = -14V		0.01	2.0		0.01	5.0	nA
			V _S = -14V, V _D = 14V	-2.0	-0.02		-5.0	-0.02		
Drain OFF Leakage Current	I _{D(off)}		V _S = -14V, V _D = 14V		0.01	2.0		0.01	5.0	
			V _S = 14V, V _D = -14V	-2.0	-0.02		-5.0	-0.02		
Drain ON Leakage Current (Note 4)	I _{D(on)}	V _{in} = 0.8V	V _S = V _D = 14V		0.1	2.0		0.1	5.0	nA
			V _S = V _D = -14V	-2.0	-0.1		-5.0	-0.1		
INPUT										
Input Current with Input Voltage High	I _{NH}	V _{in} = 2.4V, V _{in} = 15V		-1.0	0.0009		-1.0	0.0009		μA
					0.005	1.0		0.005	1.0	
Input Current with Input Voltage Low	I _{NL}	V _{in} = 0V		-1.0	-0.0015		-1.0	-0.0015		μA
DYNAMIC										
Turn-ON Time	t _{on}	See Switching Time Test Circuit (Figure 1)		440	1000		440	1000		ns
Turn-OFF Time	t _{off}			70	500		70	500		
Charge Injection	Q	C _L = 1000pF, V _{GEN} = 0V, R _{GEN} = 0Ω (Figure 2)		10			10			pC
Source OFF Capacitance	C _{S(off)}	f = 140kHz V _{in} = 5V or V _S = 0V	V _S = 0V		9.0			9.0		pF
Drain OFF Capacitance	C _{D(off)}		V _D = 0V		9.0			9.0		
Channel ON Capacitance	C _{D(on)} + C _{S(on)}		V _D = V _S = 0V		25			25		
OFF Isolation Figure 3 (Note 5)		V _{in} = 5V, Z _L = 75Ω V _S = 2.0V, f = 1MHz		75			75			dB
Crosstalk Figure 4 (Channel to Channel)				90			90			

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ELECTRICAL CHARACTERISTICS (continued)

($V^+ = +15V$, $V^- = -15V$, GND = 0V, $T_A = 25^\circ C$, unless otherwise indicated.)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS						UNITS
			DG200A			DG200 B/C/D			
			MIN (Note 2)	TYP (Note 3)	MAX	MIN (Note 2)	TYP (Note 3)	MAX	
SUPPLY									
Positive Supply Current	I+	Both Channels ON or OFF V _{in} = 0 and 2.4V	180	300		200	500	μA	
Negative Supply Current	I-		-10	-0.1		-100	-0.1		

ELECTRICAL CHARACTERISTICS (Over Temperature)

($V^+ = +15V$, $V^- = -15V$, GND = 0V, T_A = Over Temperature Range, unless otherwise indicated.)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS						UNITS	
			DG200A			DG200 B/C				
			MIN	TYP	MAX	MIN	TYP	MAX		
			(Note 2) (Note 3)			(Note 2) (Note 3)				
SWITCH										
Analog Signal Range (Note 1)	V _{ANALOG}			-15		15	-15		15	V
Drain-Source ON Resistance	r _{DS(on)}	V _D = ±10V, V _{in} = 0.8V, I _S = 1mA				100			100	Ω
Source OFF Leakage Current	I _{S(off)}	V _{in} = 2.4V	V _S = 14V, V _D = -14V			100			100	nA
			V _S = -14V, V _D = 14V	-100			-100			
Drain OFF Leakage Current	I _{D(off)}		V _S = -14V, V _D = 14V			100			100	
			V _S = 14V, V _D = -14V	-100			-100			
Drain ON Leakage Current (Note 4)	I _{D(on)}	V _{in} = 0.8V	V _S = V _D = 14V			200			200	
			V _S = V _D = -14V	-200			-200			
INPUT										
Input Current/ Voltage High	I _{NH}	V _{in} = 2.4V, V _{in} = 15V		-10			-10			μA
						10		10		
Input Current/ Voltage Low	I _{NL}	V _{in} = 0V		-10			-10			

Note 1: Signals on S_X , D_X , or IN_X , exceeding V^- or V^+ will be clamped by internal diodes. LIMIT FORWARD DIODE CURRENT to maximum current ratings.

Note 2: The algebraic convention whereby the most negative value is a minimum, and the most positive is a maximum, is used in this data sheet.

Note 3: Typical values are for DESIGN AID ONLY, not guaranteed nor subject to production testing.

Note 4: $I_{D(on)}$ is leakage from driver into "ON" switch.

Note 5: "OFF" isolation = $20 \log V_S/V_D$, V_S = input to OFF switch, V_D = output.

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Test Circuits

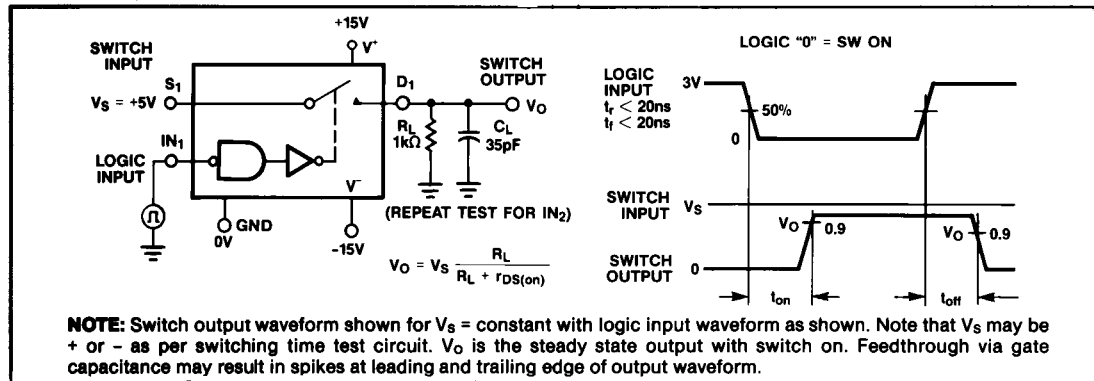


Figure 1. Switching Time Test Circuit

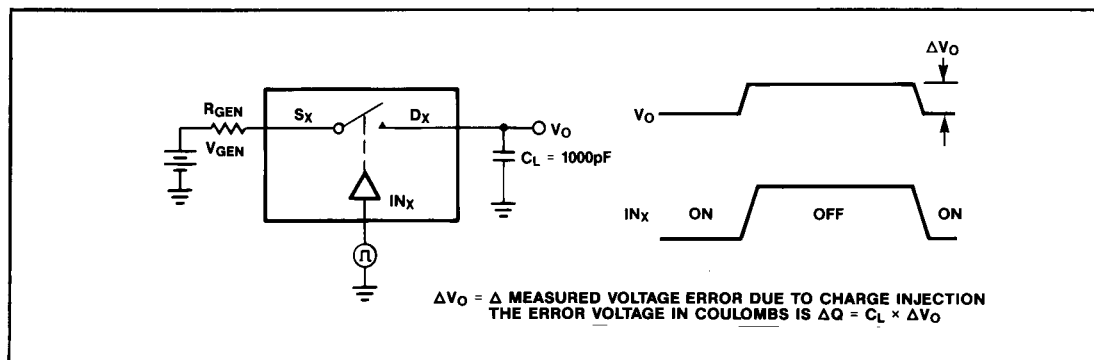


Figure 2. Charge Injection Test Circuit

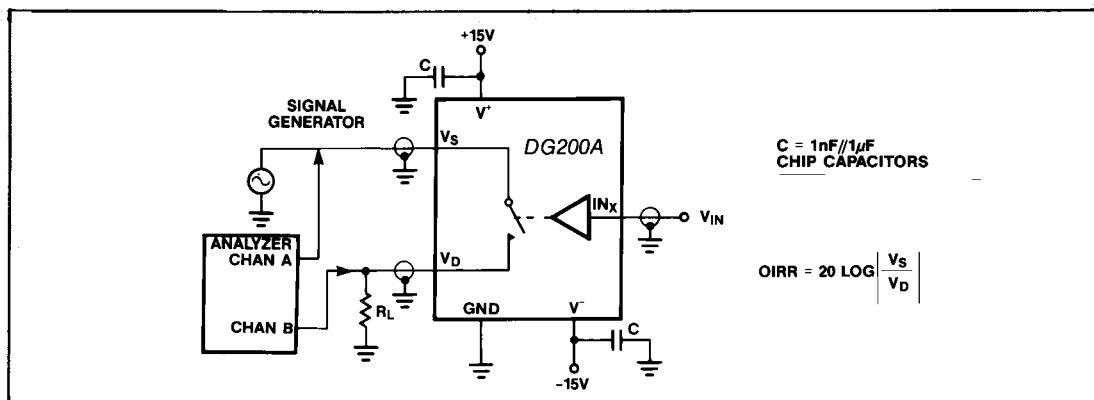


Figure 3. OFF Isolation Test Circuit

DG200A

$C = .001\mu F // .1\mu F$
CHIP CAPACITORS

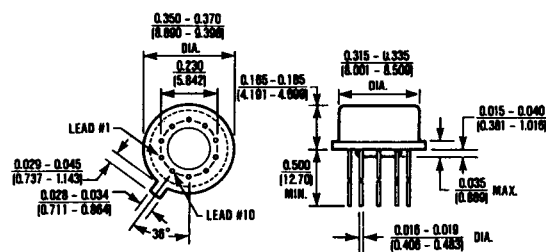
$CMRR = 20 \text{ LOG } \left| \frac{V_{S1}}{V_{D2}} \right|$

Chip Topography

Figure 1 is a detailed layout diagram of a 16-bit 100-MHz CMOS SRAM. The layout is square, with a width and height of 0.080 inches (2.03mm). The diagram shows a complex arrangement of circuit blocks and interconnects. Key pads and labels include:

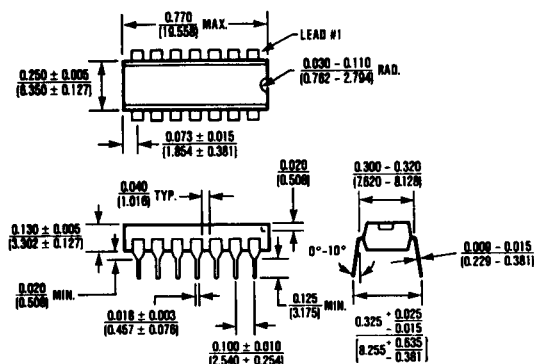
- IN₁** and **IN₂**: Input pads at the top center.
- GND**: Ground pads on the left and right sides.
- S₁** and **S₂**: Sense amplifier pads on the right and left sides, respectively.
- D₁** and **D₂**: Data output pads at the bottom right and left.
- V**: A central vertical pad at the bottom.

 The layout is symmetrical about a central vertical axis. The interconnects are dense and form a complex grid-like pattern connecting the various functional blocks and pads.

 $\theta_{JC} = 45^{\circ}\text{C/W}$

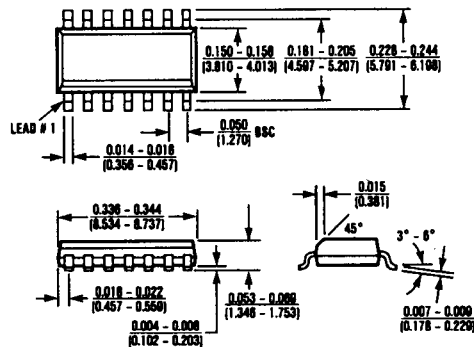
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Package Information



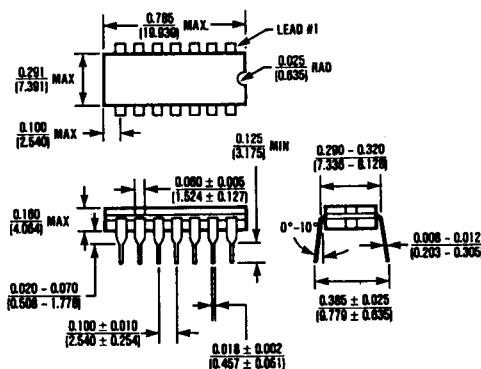
14 Lead Plastic DIP (PD)

$\theta_{JA} = 140^{\circ}\text{C/W}$
 $\theta_{JC} = 70^{\circ}\text{C/W}$



14 Lead Small Outline (SD)

$\theta_{JA} = 115^{\circ}\text{C/W}$
 $\theta_{JC} = 60^{\circ}\text{C/W}$



14 Lead Cerdip (JD)

$\theta_{JA} = 105^{\circ}\text{C/W}$
 $\theta_{JC} = 50^{\circ}\text{C/W}$

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